



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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And B
J. W. H.
7-50

In re Patent Application of:)
Shinji TAKEDA et al.) Atty. Docket No.: TM&K0008
Serial No. 09/785,486) Group Art Unit: 2814
Filed: February 20, 2001) Examiner: GRAYBILL, D.
For: SEMICONDUCTOR DEVICE AND) Date: June 19, 2002
PROCESS FOR FABRICATION)
THEREOF)

AMENDMENT (B)

Box: Fee Amendment
Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the official Office Action dated December 19, 2001, please amend the application identified above as follows:

IN THE CLAIMS:

Kindly amend claims 17-22, 40 and 43 as follows:

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17. (Amended) A material comprising an organic die-bonding film having a peel strength of 0.5 kgf/(5 mm x 5 mm chip) or higher when a semiconductor has been bonded to a support member with said material under conditions of 100-230°C temperature and pressure of 0.1-30 gf/mm².

18. (Amended) A material comprising an organic die-bonding film having the property of bonding a semiconductor chip to a support member under conditions of 100-230°C temperature